

Part Number: **DLP03LC-7**
Weight (mg): 8.62

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall	
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	8.57	0.77	1000000	89740	
Leadframe	Alloy 42	Fe	7439-89-6	57.65%	28.33	2.44	576500	163348	
		Ni	7440-02-0	41.00%			410000	116172	
		Mn	7439-96-5	0.60%			6000	1700	
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	283	
		Co	7440-48-4	0.50%			5000	1417	
		Si	7440-21-3	0.15%			1500	425	
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.20	0.10	1000000	11992	
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	1.78	0.15	1000000	17802	
		Silicone dioxide	60676-86-0	69.00%	57.72	4.98	690000	398298	
Ortho Creson Novolac Epoxy Resin	29690-82-2	12.25%	122500	70712					
Basic Duromer:Phenolic resin (Compound of polymeric network)	9003-35-4	5.50%	55000	31748					
Misc. system		12.75%	127500	73599					
Carbon black	1333-86-4	0.50%	5000	2886					
Ag	7440-22-4	75.00%	750000	9028					
Die Attach Epoxy	84-1LMISR4	epoxy resin	Trade secret	20.00%	1.20	0.10	200000	2408	
		curing agent & hardene	Trade secret	5.00%			50000	602	
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%		0.07	1000000	7840	
						Total		8.62	1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, Material Composition Declaration for Electronic Products

This product or product family does not contain any of the following substances except as CURRENTLY exempted by ELV II and RoHS and reported above:

- | | |
|--|---|
| Asbestos | Ozone Depleting Substances - Class I (CFCs, HCFCs, etc.) |
| Azo compounds | Ozone Depleting Substances - Class II (HFCs) |
| Cadmium and cadmium compounds | Perfluorooctane Sulphonate (PFOS) or related compounds |
| Certain Shortchain Chlorinated Paraffins | Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE |
| Chlorinated organic compounds | Polychlorinated Biphenyls (PCBs) |
| Hexavalent chromium compounds | Polychlorinated Naphthalenes (> 3 chlorine atoms) |
| Lead and lead compounds | Radioactive Substances |
| Mercury and mercury compounds | Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| Organic tin compounds | Tributyl Tin Oxide (TBTO) |

Part Number: **DLP05LC-(p)-F (Date Code 0833+)**
Weight (mg): 8.68

p = package designator
See Data Sheet

p= 7

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall	
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	4.29	0.37	1000000	43212	
Leadframe	Alloy 42	Fe	7439-89-6	57.65%	28.16	2.44	576500	163348	
		Ni	7440-02-0	41.00%			410000	116172	
		Mn	7439-96-5	0.60%			6000	1700	
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	283	
		Co	7440-48-4	0.50%			5000	1417	
		Si	7440-21-3	0.15%			1500	425	
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.19	0.10	1000000	11992	
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	1.77	0.15	1000000	17802	
		Silicone dioxide	60676-86-0	69.00%	61.64	5.35	690000	398298	
Ortho Creson Novolac Epoxy Resin	29690-82-2	12.25%	122500	70712					
Basic Duromer:Phenolic resin (Compound of polymeric network)	9003-35-4	5.50%	55000	31748					
Misc. system		12.75%	127500	73599					
Carbon black	1333-86-4	0.50%	5000	2886					
Ag	7440-22-4	75.00%	750000	9028					
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%		0.26	1000000	29449	
						Total		8.68	963043

Tolerance ±10%

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| Chlorinated organic compounds | Polychlorinated Biphenyls (PCBs) |
| Hexavalent chromium compounds | Polychlorinated Naphthalenes (> 3 chlorine atoms) |
| Lead and lead compounds | Radioactive Substances |
| Mercury and mercury compounds | Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| Organic tin compounds | Tributyl Tin Oxide (TBTO) |